

PRODUCT / PROCESS CHANGE NOTIFICATION	
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1. PCN basic data	
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1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MDG/24/14375
1.3 Title of PCN	AMKOR ATP (Philippines) TFBGA package copper palladium bonding wire introduction on STM32F4x, STM32F7x, STM32G4x and STM32H7x listed products.
1.4 Product Category	STM32F42/F43x, STM32F46/F47x STM32F74x, STM32F75/F76/F77x, STM32G47/G48x, STM32H72/H73x, STM32H74/H75x and STM32H7A/H7Bx
1.5 Issue date	2024-10-04

2. PCN Team	
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2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

3. Change		
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3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	AMKOR ATP (Philippines)

4. Description of change		
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	Old	New
4.1 Description	Current Wire bonding material: - MUAR (Malaysia) gold wire - ASE Kaohsiung (Taiwan) Gold or CuPd wire - AMKOR ATP (Philippines) gold wire	Current Wire bonding material: - MUAR (Malaysia) gold wire - ASE Kaohsiung (Taiwan) Gold or CuPd wire - AMKOR ATP (Philippines) gold wire New Wire bonding material : - AMKOR ATP (Philippines) copper palladium wire
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change	
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5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
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6.1 Description	traceability ensured by ST Internal tools
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7. Timing / schedule	
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7.1 Date of qualification results	2024-12-16
7.2 Intended start of delivery	2025-02-17
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14375 MDRF-GPM-RER2418 PCN14375 ATP3 TFBGA CuPd wire - products reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-10-04

9. Attachments (additional documentations)

14375 Public product.pdf
 14375 MDRF-GPM-RER2418 PCN14375 ATP3 TFBGA CuPd wire - products reliability plan.pdf
 14375 PCN14375 _Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F429NEH6	
	STM32F429NGH6	
	STM32F429NIH6	
	STM32F429NIH6TR	
	STM32F429NIH7	
	STM32F439NGH6	
	STM32F439NIH6	
	STM32F469NIH6	
	STM32F479NIH6	
	STM32F745VEH6	
	STM32F745VGH6	
	STM32F746NEH6	
	STM32F746NGH6	
	STM32F746NGH6TR	
	STM32F746NGH7	
	STM32F746VGH6	
	STM32F750N8H6	
	STM32F756NGH6	
	STM32F765NGH6	
	STM32F765NIH6	
	STM32F765NIH7	
	STM32F765VGH6	
	STM32F765VIH6	
	STM32F767NGH6	
	STM32F767NIH6	
	STM32F767NIH7	
	STM32F767VIH6	
	STM32F769NGH6	
	STM32F769NIH6	
	STM32F777NIH6	
	STM32F777VIH6	
	STM32F779NIH6	
	STM32G473VBH6	
	STM32G473VEH6	
	STM32G474VEH6	
	STM32G484VEH6	
	STM32H723VGH6	
	STM32H743VIH6	
	STM32H743XIH6	

	STM32H745XGH6	
	STM32H745XIH6	
	STM32H747XIH6	
	STM32H750XBH6	
	STM32H753VIH6	
	STM32H753XIH6	
	STM32H755XIH3	
	STM32H755XIH6	
	STM32H757XIH6	
	STM32H7A3LIH6Q	

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Public Products List

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PCN Title : AMKOR ATP (Philippines) TFBGA package copper palladium bonding wire introduction on STM32F4x, STM32F7x, STM32G4x and STM32H7x listed products.

PCN Reference : MDG/24/14375

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F479NIH6	STM32F429NIH7	STM32F429NIH6TR
STM32H745XIH3	STM32H7A3VGH6	STM32F777NIH7TR
STM32H755XIH3	STM32H742XIH6	STM32F439NIH6
STM32H757XIH6	STM32F479NGH6	STM32G474VCH3TR
STM32F756VGH6	STM32F439NGH6	STM32H7B3NIH6
STM32H730VBH6	STM32F469NIH6TR	STM32F769NGH6
STM32H753VIH6	STM32F767VIH6	STM32H753XIH6TR
STM32H755XIH6TR	STM32F765NGH7TR	STM32H750XBH6
STM32F429NGH6	STM32F429NIH6	STM32H742XGH6
STM32H745XIH3TR	STM32H745XIH6	STM32F769NIH6
STM32F765NIH6TR	STM32G484VEH6	STM32H755XIH6
STM32H7A3VIH6	STM32F767VGH6	STM32H753XIH6
STM32H745XGH6	STM32F745VEH6	STM32H747XIH6
STM32H742VIH6	STM32H735VGH6	STM32H747XGH6
STM32H743VIH6TR	STM32F777NIH6	STM32H745XIH6TR
STM32G474VBH6	STM32F746VGH6	STM32F765NGH6
STM32F750N8H6	STM32H7A3LGH6Q	STM32F765VGH6TR
STM32H723VEH6	STM32H743XIH6	STM32F746VEH6
STM32F765NIH7	STM32H7B3LIH6Q	STM32F746NGH7
STM32F469NIH7	STM32H755XIH3TR	STM32F469NEH6
STM32F746NGH6TR	STM32F746NGH6	STM32G483VEH6
STM32H723VGH6	STM32F765VIH6	STM32H7A3LIH6Q
STM32F429NEH6	STM32F767NIH7	STM32F777VIH7
STM32H743VIH6	STM32H742VGH6	STM32F756NGH6
STM32F745VGH6	STM32G473VEH6	STM32F745VEH6TR
STM32H742VIH6TR	STM32F767NIH6	STM32H743XGH6
STM32G473VEH3	STM32H7B3VIH6Q	STM32F746NEH6
STM32H7A3NIH6	STM32F767NIH6TR	STM32F777VIH6
STM32F469NGH6	STM32G474VCH6	STM32H7A3VIH6Q
STM32H7A3NGH6	STM32F779NIH6	STM32H7B3VIH6
STM32H743VGH6	STM32G474VEH6	STM32F767NGH6
STM32F765VGH6	STM32H725VGH3	STM32G474VEH3
STM32F469NIH6	STM32G473VCH3	STM32H7A3VGH6Q
STM32G473VCH3TR	STM32F765NGH7	STM32H725VEH6
STM32H725VGH6	STM32F765NIH6	STM32F777NIH7

STM32G473VBH3	STM32H733VGH6	STM32G473VCH6
STM32G474VCH3	STM32G473VBH6	STM32G473VEH6TR

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